

1.6 x 1.6 x 0.5mm Blue & Red & Pure Green SMD

OSTF1616C1C

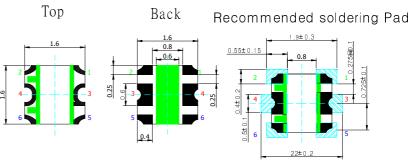
■Features

- Full-Color
- Super high brightness of surface mount LED
- Water Clear Flat Mold
- Compact package outline
 (LxWxT) of 1.6mm x 1.6mm x 0.5mm
- Compatible to IR reflow soldering.

Applications

Backlighting (switches, keys, etc.)

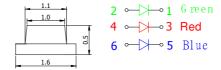
Marker lights (e.g. steps, exit ways, etc.)



■Outline Dimension

Side

(Ta=25°C)



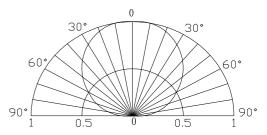
Notes: 1. All dimensions are in millimeters;

2. Tolerance is \pm 0.10 mm unless otherwise noted.

■Absolute Maximum Rating

Item	Carrala a 1	Va	T I:4		
nem	Symbol	HR	PG/BL	Unit	
DC Forward Current	I_F	25	25	mA	
Pulse Forward Current*	I_{FP}	100	100	mA	
Reverse Voltage	V_R	5	5	V	
Power Dissipation	P_{D}	65	90	mW	
Operating Temperature	Topr	-40 ~	$^{\circ}\! \mathbb{C}$		
Storage Temperature	Tstg	-40~	$^{\circ}\! C$		
Lead Soldering Temperature	Tsol	260°C	-		

Directivity



■Electrical -Optical Characteristics

(Ta=25°C)

				$V_{F}(V)$		$I_R(\mu A)$	Iv(mcd)		λD(nm)			2θ1/2(deg)		
Part Number	imber Color			Min.	Тур.	Max.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Тур.
				I _F =20mA		V _R =5V	I _F =20mA							
	Blue	BL		2.8	3.0	3.6	10	50	80	-	465	470	475	120
OSTF1616C1C	Pure Green	PG		2.8	3.0	3.6	10	450	600	-	520	525	530	120
	Red	HR		1.8	2.0	2.6	10	180	250	-	617	625	630	120

^{*1} Tolerance of measurements of dominant wavelength is ±1nm

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^{*}Pulse width Max 0.1ms, Duty ratio max 1/10

^{*2} Tolerance of measurements of luminous intensity is ±15%

^{*3} Tolerance of measurements of forward voltage is ± 0.1 V

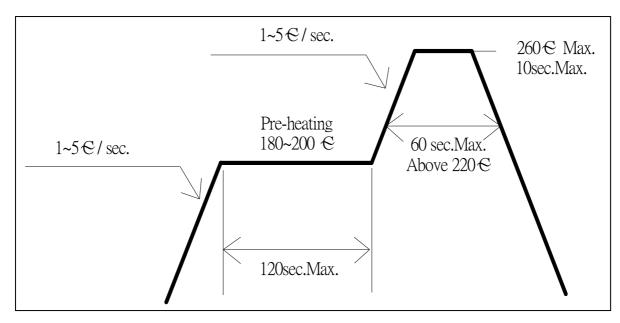


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■ Soldering Conditions

	Reflow Soldering	Hand Soldering			
Pre-Heat	180 ~ 200°C				
Pre-Heat Time	120 sec. Max.				
Peak temperature	260°C Max.	Temperature	350°C Max. 3 sec. Max.		
Dipping Time	10 sec. Max.	Soldering time			
Condition	Refer to Temperature-profile		(one time only)		

• Reflow Soldering Condition(Lead-free Solder)



- *Recommended soldering conditions vary according to the type of LED
- *Although the recommended soldering conditions are specified in the above table, reflow, or hand soldering at the lowest possible temperature is desirable for the LEDs.
- *A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.
- •All SMD LED products are pb-free soldering available.
- Occasionally there is a brightness decrease caused by the influence of heat or ambient atmosphere during air reflow. It is recommended that the User use the nitrogen reflow method.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.









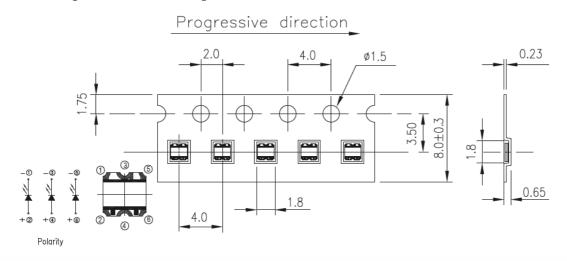
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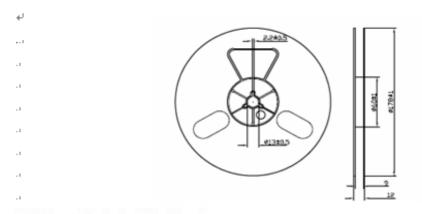


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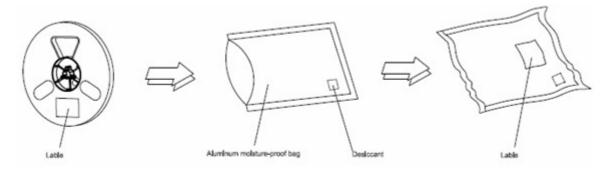
■ Reel & Tape Dimensions (2000pcs/reel):



Reel Dimensions₽



Moisture Resistant Packaging 4



Note:The tolerances unless mentioned is ±0.1mm,Unit:mm ...

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